# **Surface Mount Schottky Power Rectifier**

## **SMB Power Surface Mount Package**

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop

#### **Mechanical Characteristics:**

- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8"
- Weight: 95 mg (approximately)
- Cathode Polarity Band
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Available in 12 mm Tape, 2500 Units per 13" Reel, Add "T3" Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Marking: 2BL4

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 100$ °C)	I <sub>O</sub>	2.0	Α
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 105°C)	I <sub>FRM</sub>	4.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	25	Α
Storage/Operating Case Temperature	T <sub>stg</sub> , T <sub>C</sub>	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +125	°C
Voltage Rate of Change (Rated V <sub>R</sub> , T <sub>J</sub> = 25°C)	dv/dt	10,000	V/µs



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## SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES 40 VOLTS



SMB CASE 403A PLASTIC

#### MARKING DIAGRAM



2BL4 = Device Code

## ORDERING INFORMATION

Device	Package	Shipping
MBRS240LT3	SMB	2500/Tape & Reel

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction–to–Lead (Note 1.)	$R_{\theta JL}$	18	°C/W
Thermal Resistance — Junction–to–Ambient (Note 3.)	$R_{\theta JA}$	78	

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 2.)		V <sub>F</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 125°C	Volts
see Figure 2	$(I_F = 2.0 \text{ A})$ $(I_F = 4.0 \text{ A})$		0.43 0.54	0.375 0.55	
Maximum Instantaneous Reverse Current (Note 2.)		I <sub>R</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	mA
see Figure 4	$(V_R = 40 \text{ V})$ $(V_R = 20 \text{ V})$		2.0 0.5	60 40	

- Mounted with minimum recommended pad size, PC Board FR4.
- Pulse Test: Pulse Width ≤ 250 µs, Duty Cycle ≤ 2.0%.
   1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

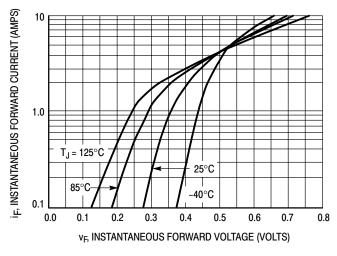


Figure 1. Typical Forward Voltage

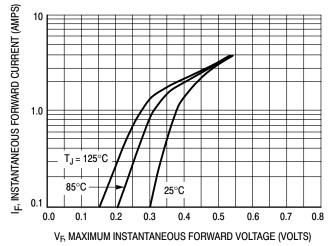
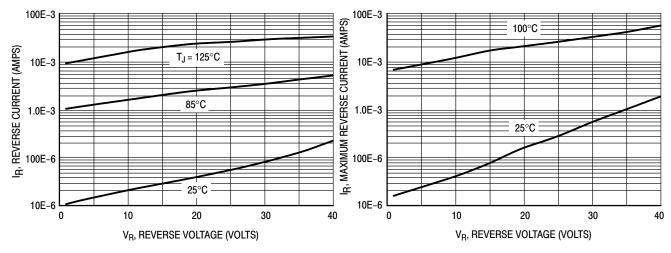
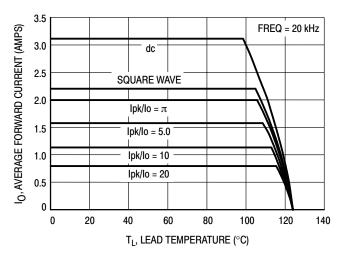


Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

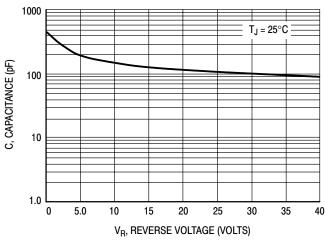
Figure 4. Maximum Reverse Current



P<sub>FO</sub>, AVERAGE POWER DISSIPATION (WATTS) 1.6 dc 1.4 SQUARE WAVE  $\text{lpk/lo} = \pi$ 1.2 lpk/lo = 5.0 1.0 lpk/lo = 108.0 Ipk/Io = 20 0.6 0.4 0.2 1.5 2.5 3.5 0 0.5 1.0 2.0 3.0 IO, AVERAGE FORWARD CURRENT (AMPS)

Figure 5. Current Derating

Figure 6. Forward Power Dissipation



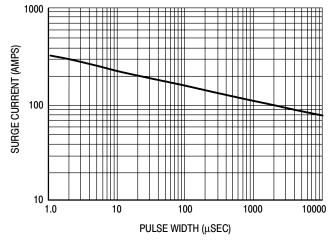


Figure 7. Capacitance

Figure 8. Maximum Non-Repetitive Forward Surge Current

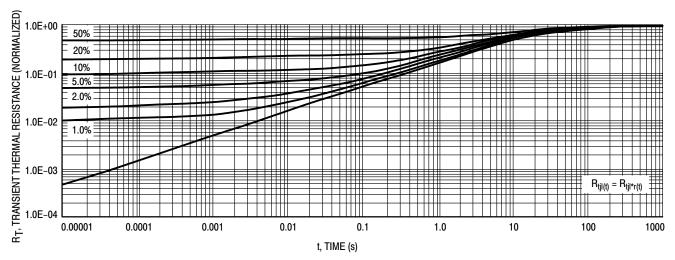
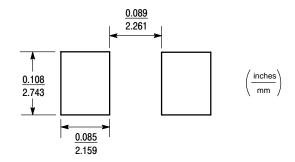
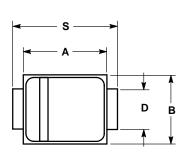


Figure 9. Thermal Response

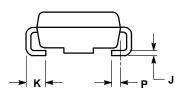
#### MINIMUM SOLDER PAD SIZES

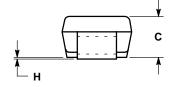


#### PACKAGE DIMENSIONS



#### **SMB** PLASTIC PACKAGE CASE 403A-03 ISSUE D





#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- D DIMENSION SHALL BE MEASURED WITHIN
- DIMENSION P.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
Р	0.020 REF		0.51 REF		
S	0.205	0.220	5.21	5.59	

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